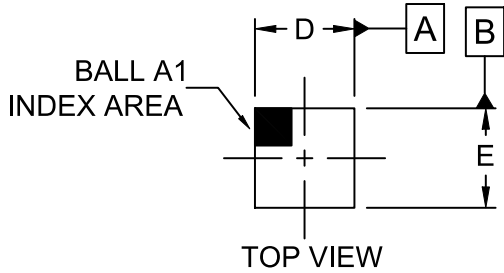


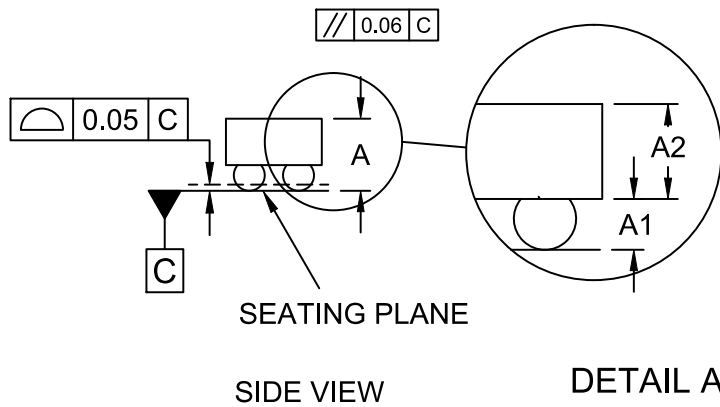
**WLCSP4, 0.815x0.815x0.457**  
CASE 567VT  
ISSUE O

DATE 31 JAN 2018

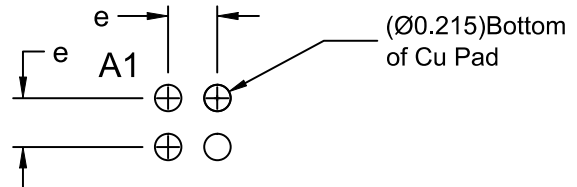
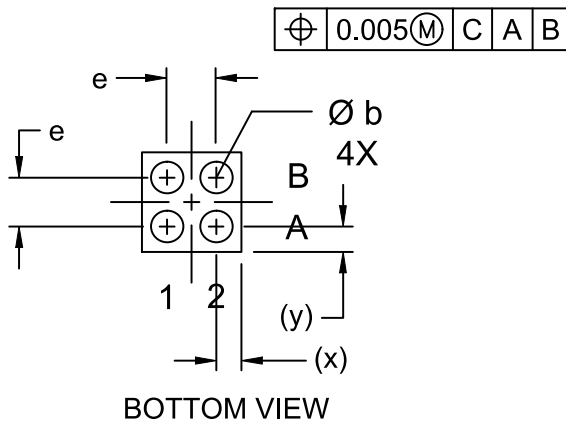


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.419	0.457	0.495
A1	0.183	0.203	0.223
A2	0.236	0.254	0.272
b	0.240	0.260	0.280
D	0.785	0.815	0.845
E	0.785	0.815	0.845
e	0.40 BSC		
x	0.1925	0.2075	0.2225
y	0.1925	0.2075	0.2225



(NSMD PAD TYPE)

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<b>DESCRIPTION:</b>	<b>WLCSP4, 0.815x0.815x0.457</b>	<b>PAGE 1 OF 1</b>

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